3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD (HBM) PROTECTION

SLLS349J - JUNE 1999 - REVISED MARCH 2004

- RS-232 Bus-Pin ESD Protection Exceeds ±15 kV Using Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Operates Up To 250 kbit/s
- Five Drivers and Three Receivers
- Low Standby Current . . . 1 μA Typical
- External Capacitors . . . 4 × 0.1 μF
- Accepts 5-V Logic Input With 3.3-V Supply
- Always-Active Noninverting Receiver Output (ROUT1B)
- Alternative High-Speed Pin-Compatible Device (1 Mbit/s)
 - SNx5C3238
- Applications
 - Battery-Powered Systems, PDAs, Notebooks, Subnotebooks, Laptops, Palmtop PCs, Hand-Held Equipment, Modems, and Printers

DB OR PW PACKAGE (TOP VIEW) C2+ C1+ GND 2 27 7 V+ C2- 13 26 VCC V- \ 4 25 C1-DOUT1 5 24 **∏** DIN1 DOUT2 6 23 DIN2 DOUT3 17 22 □ DIN3 RIN1 8 21 | ROUT1 RIN2 9 20 **∏** ROUT2 19 DIN4 DOUT4 10 18 ROUT3 RIN3 11 DOUT5 12 17 **□** DIN5 FORCEON 13 16 ROUT1B 15 INVALID FORCEOFF

description/ordering information

The MAX3238 consists of five line drivers, three line receivers, and a dual charge-pump circuit with ±15-kV ESD (HBM) protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between notebook and subnotebook computer applications. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT1B), which allows applications using the ring indicator to transmit data while the device is powered down. These devices operate at data signaling rates up to 250 kbit/s and a maximum of 30-V/µs driver output slew rate.

ORDERING INFORMATION

TA	PACKAGI	ΕŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0000 (DD)	Tube of 50	MAX3238CDB	MAYOOOO
2001 7000	SSOP (DB)	Reel of 2000	MAX3238CDBR	MAX3238C
−0°C to 70°C	T000D (D)40	Tube of 50	MAX3238CPW	1440000 75C-
	TSSOP (PW)	Reel of 2000	MAX3238CPWR	MA3238C
	0000 (DD)	Tube of 50	MAX3238IDB	MANAGOOD
4000 / 0500	SSOP (DB)	Reel of 2000	MAX3238IDBR	MAX3238I
-40°C to 85°C	TOOOD (DIA)	Tube of 50	MAX3238IPW	MPOODOL
E	TSSOP (PW)	Reel of 2000	MAX3238IPWR	MB3238I

Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



MAX3238

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WITH ±15-kV ESD (HBM) PROTECTION SLLS349J – JUNE 1999 – REVISED MARCH 2004

description/ordering information (continued)

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-powerdown plus feature functions when FORCEON is low and $\overline{\text{FORCEOFF}}$ is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1 μ A. By disconnecting the serial port or placing the peripheral drivers off, auto-powerdown plus occurs if there is no activity in the logic levels for the driver inputs. Auto-powerdown plus can be disabled when FORCEON and $\overline{\text{FORCEOFF}}$ are high. With auto-powerdown plus enabled, the device activates automatically when a valid signal is applied to any receiver or driver input. $\overline{\text{INVALID}}$ is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than $30~\mu$ s. Refer to Figure 5 for receiver input levels.

Function Tables

EACH DRIVER

		INI	PUTS	OUTPUT	
DIN	FORCEON	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	DOUT	DRIVER STATUS
Х	Χ	L	X	Z	Powered off
L	Н	Н	X	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown plus disabled
L	L	Н	<30 s	Н	Normal operation with
Н	L	Н	<30 s	L	auto-powerdown plus enabled
L	L	Н	>30 s	Z	Powered off by
Н	L	Н	>30 s	Z	auto-powerdown plus feature

H = high level, L = low level, X = irrelevant, Z = high impedance

FACH RECEIVER

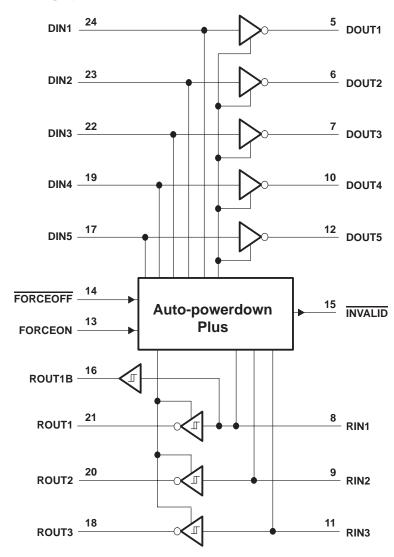
			EACH RECEIVER			
		INP	UTS	OUTP	UTS	
RIN1	RIN2-RIN3	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	ROUT1B	ROUT	RECEIVER STATUS
L	Χ	L	X	L	Z	Powered off while
Н	Χ	L	X	Н	Z	ROUT1B is active
L	L	Н	<30 s	L	Н	
L	Н	Н	<30 s	L	L	Normal operation with
Н	L	Н	<30 s	Н	Н	auto-powerdown plus
Н	Н	Н	<30 s	Н	L	disabled/enabled
Open	Open	Н	>30 s	L	Н	

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off



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logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	
Negative output supply voltage range, V– (see Note 1)	0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1)	13 V
Input voltage range, V _I : Driver (FORCEOFF, FORCEON)	
Receiver	–25 V to 25 V
Output voltage range, VO: Driver	
Receiver (INVALID)	0.3 V to V _{CC} + 0.3 V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package	62°C/W
PW package	62°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{sto}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
 - 2. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
	Cumhicueltage		V _{CC} = 3.3 V	3	3.3	3.6	V
	Supply voltage		$V_{CC} = 5 V$	4.5	5	5.5	V
V	Duises and control bink level innertualtees	DIN, FORCEOFF, FORCEON	$V_{CC} = 3.3 \text{ V}$	2			V
VIH	Driver and control high-level input voltage		$V_{CC} = 5 V$	2.4			V
V_{IL}	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON				0.8	V
٧ _I	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
٧ _I	Receiver input voltage			-25		25	V
т.			MAX3238C	0		70	°C
TA	Operating free-air temperature		MAX3238I	-40		85	-0

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 $V \pm 0.15$ V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 $V \pm 0.3$ V; and C1 = 0.047 μ F and C2–C4 = 0.33 μF at V $_{CC}$ = 5 V \pm 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT	
П	Input leakage current	FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown plus disabled	No load, FORCEOFF and FORCEON at V _{CC}		0.5	2	mA
Icc	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
.00	$(T_A = 25^{\circ}C)$	Auto-powerdown plus enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

[‡] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μF at V $_{CC}$ = 5 V \pm 0.5 V.



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DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TES	ST CONDITIONS	6	MIN	TYP [†]	MAX	UNIT
Vон	High-level output voltage	All DOUT at R _L = $3 \text{ k}\Omega$ to	All DOUT at R _L = 3 k Ω to GND			5.4		V
VOL	Low-level output voltage	All DOUT at R _L = 3 k Ω to GND		-5	-5.4		V	
ΙΙΗ	High-level input current	$V_I = V_{CC}$				±0.01	±1	μΑ
Ι _Ι Γ	Low-level input current	V _I at GND				±0.01	±1	μΑ
Γ.		VCC = 3.6 V,	VO = 0 V			±35	±60	A
los	Short-circuit output current‡	V _{CC} = 5.5 V,	V _O = 0 V			±40	±100	mA
r _O	Output resistance	V_{CC} , V+, and V- = 0 V,	V _O = ±2 V		300	10M		Ω
1	Outrat la also as assument	FORCEOFF = GND	$V_0 = \pm 12 \text{ V},$	$V_{CC} = 3 V \text{ to } 3.6 V$			±25	
loff	Output leakage current	FURGEOFF = GND	$V_0 = \pm 10 \text{ V},$	V _{CC} = 4.5 V to 5.5 V			±25	μA

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS			TYP†	MAX	UNIT
	Maximum data rate	C _L = 1000 pF, One DOUT switching,	$R_L = 3 k\Omega$, See Figure 1	150	250		kbit/s
tsk(p)	Pulse skew§	C _L = 150 pF to 2500 pF	R_L = 3 kΩ to 7 kΩ, See Figure 2		100		ns
SR(tr)	Slew rate, transition region	V _{CC} = 3.3 V,	C _L = 150 pF to 1000 pF	6		30	Muc
SK(II)	(see Figure 1)	$R_L = 3 k\Omega$ to $7 k\Omega$	C _L = 150 pF to 2500 pF	4		30	V/μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.



^{\$} Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

[§] Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μF at V_{CC} = 5 V \pm 0.5 V.

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RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Vон	High-level output voltage	I _{OH} = -1 mA	V _{CC} -0.6 V	V _{CC} -0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
.,	Decition and a femal three held college	V _{CC} = 3.3 V		1.5	2.4	.,
V _{IT+}	Positive-going input threshold voltage	V _{CC} = 5 V		1.8	2.4	V
.,	No nether restant to and though all cells as	V _{CC} = 3.3 V	0.6	1.2		.,
V _{IT} _	Negative-going input threshold voltage	V _{CC} = 5 V	0.8	1.5		V
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})			0.3		V
l _{off}	Output leakage current (except ROUT1B)	FORCEOFF = 0 V		±0.05	±10	μΑ
rį	Input resistance	$V_1 = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 μ F and C2-C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

	PARAMETER	TEST CONDITIONS	MIN TYPT MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	0 450 55 0 5 5 5 5 5 5 5	150	ns
tPHL	Propagation delay time, high- to low-level output	C _L = 150 pF, See Figure 3	150	ns
t _{en}	Output enable time	C. 450 pF D. 240 Coo Figure 4	200	ns
tdis	Output disable time	C_L = 150 pF, R_L = 3 kΩ, See Figure 4	200	ns
tsk(p)	Pulse skew [‡]	See Figure 3	50	ns

 $[\]overline{\dagger}$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



[‡] Pulse skew is defined as |tplh - tphl| of each channel of the same device.

AUTO-POWERDOWN PLUS SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{T+(valid)}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}			2.7	V
V _T –(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7			V
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3		0.3	V
VOH	INVALID high-level output voltage	I _{OH} = -1 mA, FORCEON = GND, FORCEOFF = V _{CC}	V _{CC} -0.6			V
VOL	INVALID low-level output voltage	I _{OL} = 1.6 mA, FORCEON = GND, FORCEOFF = V _{CC}			0.4	V

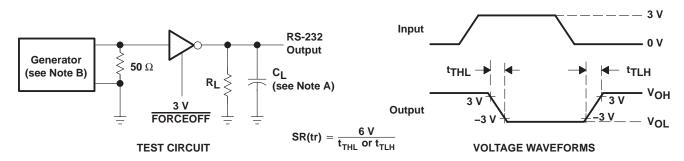
 $[\]dagger$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	MIN	TYP [†]	MAX	UNIT
t _{valid}	Propagation delay time, low- to high-level output		0.1		μs
^t invalid	Propagation delay time, high- to low-level output		50		μs
t _{en}	Supply enable time		25		μs
^t dis	Receiver or driver edge to auto-powerdown plus	15	30	60	s

 $[\]dagger$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

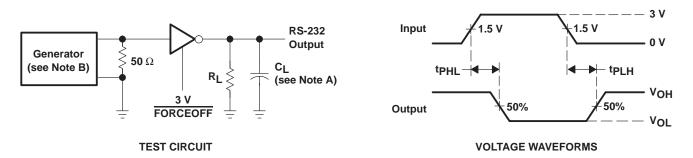
B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 1. Driver Slew Rate



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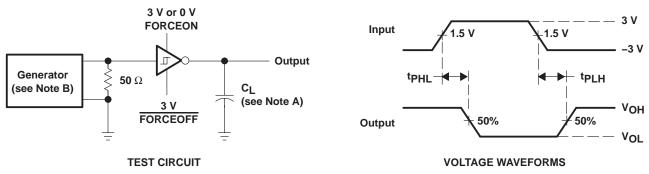
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

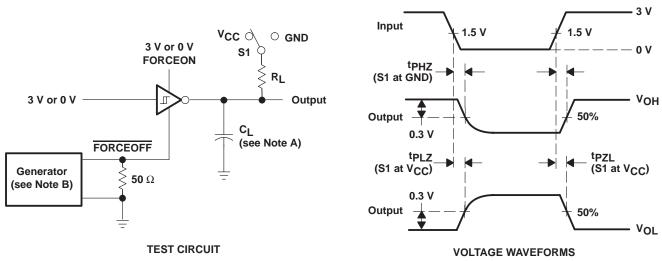
Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_Q = 50 \Omega$, 50% duty cycle, $t_{\Gamma} \le 10$ ns, $t_{\Gamma} \le 10$ ns.

Figure 3. Receiver Propagation Delay Times



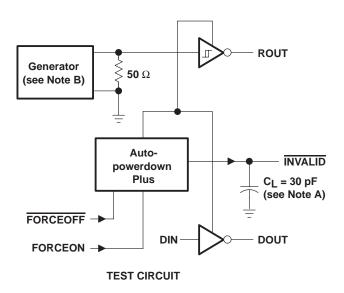
NOTES: A. C_L includes probe and jig capacitance.

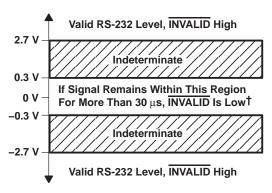
- B. The pulse generator has the following characteristics: $Z_O = 50 \ \Omega$, 50% duty cycle, $t_\Gamma \le 10 \ ns$, $t_f \le 10 \ ns$.
- C. tpLZ and tpHZ are the same as tdis.
- D. tpzL and tpzH are the same as ten.

Figure 4. Receiver Enable and Disable Times



PARAMETER MEASUREMENT INFORMATION





† Auto-powerdown plus disables drivers and reduces supply current to 1 µA.

- NOTES: A. C_L includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: PRR = 5 kbit/s, Z_0 = 50 Ω , 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

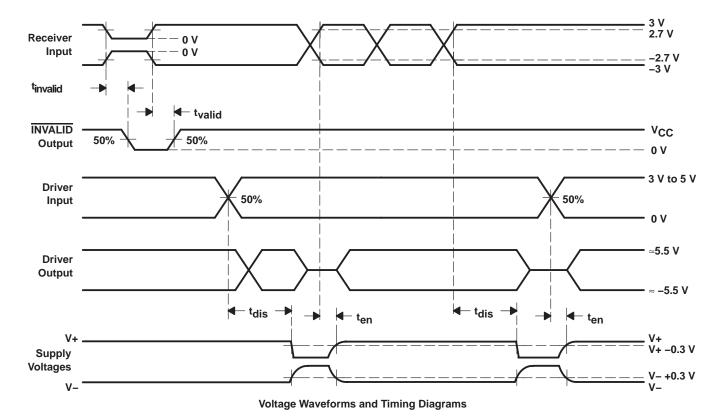
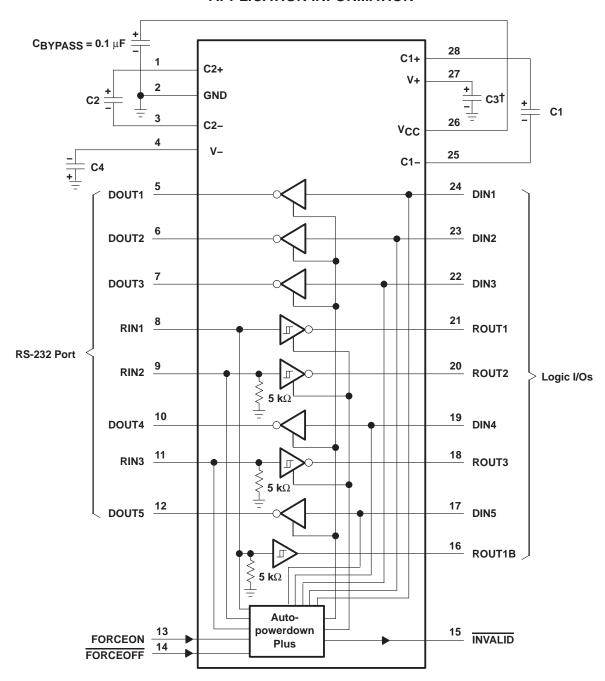


Figure 5. INVALID Propagation-Delay Times and Supply-Enabling Time



APPLICATION INFORMATION



V_{CC} vs CAPACITOR VALUES

†C3 can be connected to VCC or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

VCC	C1	C2, C3, and C4
$\begin{array}{c} 3.3 \text{ V} \pm 0.15 \text{ V} \\ 3.3 \text{ V} \pm 0.3 \text{ V} \\ 5 \text{ V} \pm 0.5 \text{ V} \\ 3 \text{ V to } 5.5 \text{ V} \end{array}$	0.1 μF 0.22 μF 0.047 μF 0.22 μF	0.1 μF 0.22 μF 0.33 μF 1 μF

Figure 6. Typical Operating Circuit and Capacitor Values





5-Dec-2005



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
MAX3238CDB	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238CDBE4	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238CDBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238CDBRE4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238CDBRG4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
MAX3238CPW	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238CPWR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238IDB	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238IDBE4	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238IDBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238IDBRE4	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238IPW	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238IPWE4	ACTIVE	TSSOP	PW	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238IPWR	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MAX3238IPWRE4	ACTIVE	TSSOP	PW	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

5-Dec-2005

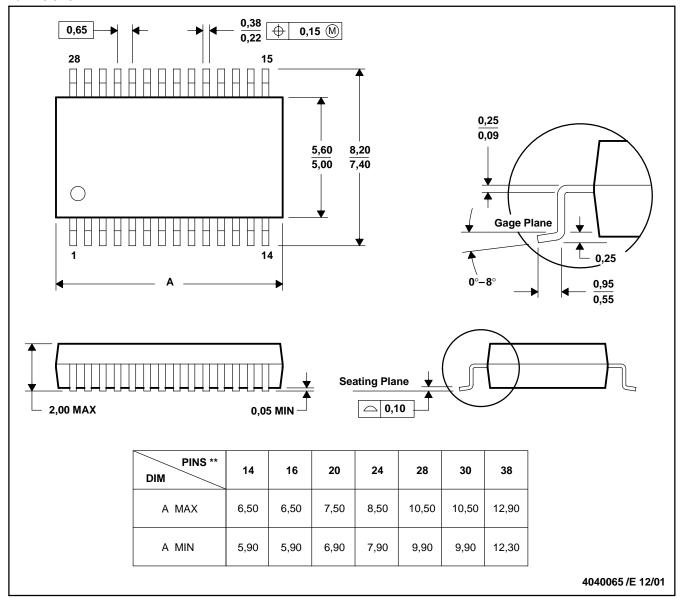
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DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

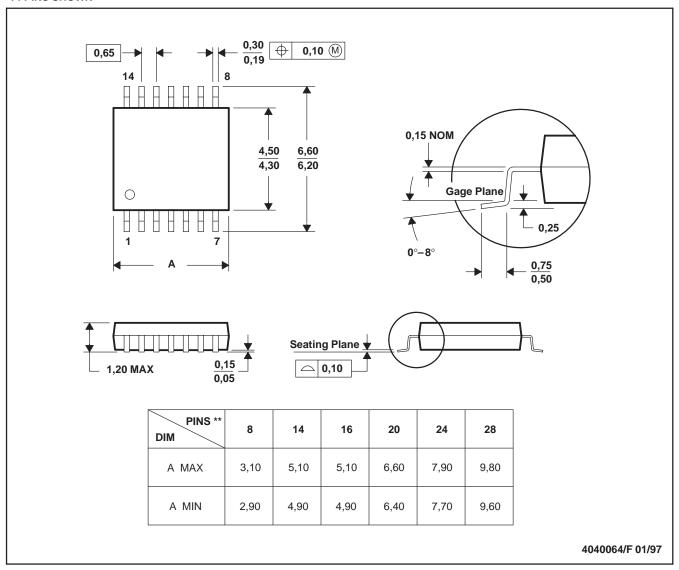
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153

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